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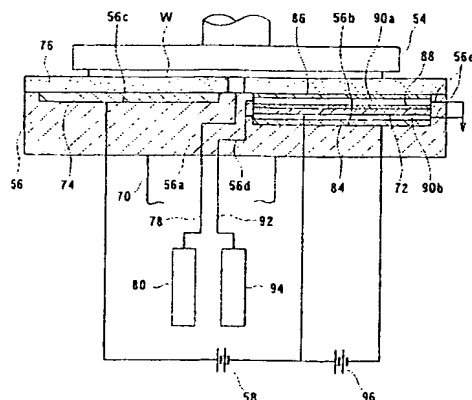
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(54) Title: ELECTROLYTIC PROCESSING APPARATUS



(57) Abstract: An electrolytic processing apparatus (50) has feed electrodes (74) to feed a current to a substrate (W), an ion ex-
changer (76) brought into contact with the substrate (W), and process electrodes (72) to perform an electrolytic process on the
substrate (W). The electrolytic processing apparatus (50) has an electrolytic processing liquid source to supply an electrolytic
processing liquid between the substrate (W) and the ion exchanger (76), and a regeneration liquid supply source to supply a regeneration
liquid to a regeneration liquid chambers (90a, 90b). The electrolytic processing apparatus (50) includes regeneration electrodes (84)
spaced from the process electrodes (72). The feed electrode (74) has a potential higher than the process electrode (72) and the same
polarity as the process electrode (72). The process electrode (72) has a potential higher than the regeneration electrode (84).